g		GE Energ	у	Functio	nal Testing Spe	cification		
Parts & Repair Services Louisville, KY			LOU-GED-531X124MSD					
	Test Procedure MFC suppression card							
DOCU	DOCUMENT REVISION STATUS: Determined by the last entry in the "REV" and "DATE" column							
REV.		DESCRIPTION	<u> </u>		SIGNATURE	REV. DATE		
Α	Initial release				James Archibald	6/27/2011		
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1. SCOPE

1.1 This is a functional testing procedure for a Card.

2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

3. APPLICABLE DOCUMENTS

- **3.1** The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.
 - **3.1.1** Check board's electronic folder for more information

4. **ENGINEERING REQUIREMENTS**

- 4.1 Equipment Cleaning
 - **4.1.1** Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to site specific SRA's for cleaning guidelines.
- **4.2** Equipment Inspection
 - **4.2.1** Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:
 - 4.2.1.1 Wires broken, cracked, or loosely connected
 - 4.2.1.2 Terminal strips / connectors broken or cracked
 - 4.2.1.3 Components visually damaged
 - **4.2.1.4** Capacitors bloated or leaking
 - 4.2.1.5 Solder joints damaged or cold
 - 4.2.1.6 Circuit board burned or de-laminated
 - 4.2.1.7 Printed wire runs / Traces burned or damaged

5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description
1		Fluke 85 DMM (or Equivalent)

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6. TESTING PROCESS

- **6.1** Set DVM to resistance.
 - 6.1.1 Measure from K1 to DW meter should read 112K +/- 10%
 - **6.1.2** Measure from K2 to DW meter should read 112K +/- 10%
 - **6.1.3** Measure from K2 to K3 meter should read infinity
 - **6.1.4** Measure from K1 to K3 meter should read infinity.
 - **6.1.5** Measure from AF to DW meter should read infinity.
 - 6.1.6 Measure across R37 & 38 meter should read 82 ohms +/- 10%
 - 6.1.7 Measure from FCPL pin 1 to pin 2 meter should read 20 ohms +/- 10%
 - **6.1.8** Measure from KF to K3 on coil meter should read 0 ohms, +/- 0.5 ohms.
 - **6.1.9** Measure from DZ to AF on coil, meter should read 0 ohms, +/- 0.5 ohms.
- **6.2** Put DVM on capacitance.
 - **6.2.1** Measure from DZ to C7 closest to R37 and meter should read .1 UF +/- 10%.
 - **6.2.2** Measure from AF to C6 closest to the bottom of the card meter should read 0.1 UF +/-10%.
- 6.3 ***TEST COMPLETE **

7. NOTES

7.1 None at this time.

8. ATTACHMENTS

8.1 None at this time.